

RGCL80TS60D

600V 40A Field Stop Trench IGBT

V _{CES}	600V
I _{C(100°C)}	40A
V _{CE(sat) (Typ.)}	1.4V
P_D	148W

Features

- 1) Low Collector Emitter Saturation Voltage
- 2) Soft Switching
- 3) Built in Very Fast & Soft Recovery FRD (RFN Series)
- 4) Pb free Lead Plating; RoHS Compliant

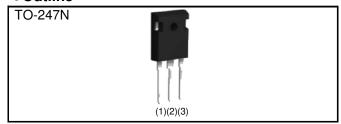
Applications

Partial Switching PFC

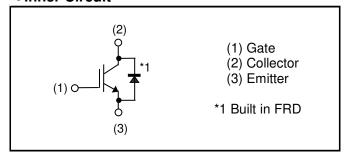
Discharge Circuit

Brake for Inverter

Outline



●Inner Circuit



Packaging Specifications

	Packaging	Tube	
		Reel Size (mm)	-
_	vno.	Tape Width (mm)	-
'	ype	Basic Ordering Unit (pcs)	450
		Taping Code	C11
		Marking	RGCL80TS60D

● Absolute Maximum Ratings (at T_C = 25°C unless otherwise specified)

Parameter		Symbol	Value	Unit
Collector - Emitter Voltage		V _{CES}	600	V
Gate - Emitter Voltage		V_{GES}	±30	V
Callactor Current	T _C = 25°C	I _C	65	А
Collector Current	$T_C = 100$ °C	I _C	40	А
Pulsed Collector Current		I _{CP} *1	160	А
Diode Forward Current	T _C = 25°C	I _F	35	А
	$T_C = 100$ °C	I _F	20	А
Diode Pulsed Forward Current		I _{FP} *1	100	А
Daway Dissination	T _C = 25°C	P _D	148	W
Power Dissipation	T _C = 100°C	P _D	74	W
Operating Junction Temperature		T _j	-40 to +175	°C
Storage Temperature		T _{stg}	-55 to +175	°C

^{*1} Pulse width limited by T_{imax}.

●Thermal Resistance

Parameter	Cumbal	Values			Unit
Farameter	Symbol	Min.	Тур.	Max.	Offic
Thermal Resistance IGBT Junction - Case	$R_{\theta(j-c)}$	-	-	1.01	°C/W
Thermal Resistance Diode Junction - Case	$R_{\theta(j-c)}$	-	-	2.28	°C/W

ullet IGBT Electrical Characteristics (at $T_j = 25$ °C unless otherwise specified)

Parameter	Symbol	Conditions	Values			Unit	
r ai ainetei	Syllibol	Conditions	Min.	Тур.	Max.	UTIIL	
Collector - Emitter Breakdown Voltage	BV _{CES}	$I_C = 10 \mu A, V_{GE} = 0 V$	600	-	-	V	
Collector Cut - off Current	I _{CES}	$V_{CE} = 600V, V_{GE} = 0V$	ı	1	10	μΑ	
Gate - Emitter Leakage Current	I _{GES}	$V_{GE} = \pm 30V$, $V_{CE} = 0V$	-	-	±200	nA	
Gate - Emitter Threshold Voltage	$V_{GE(th)}$	$V_{CE} = 5V, I_{C} = 30.0 \text{mA}$	4.5	5.5	6.5	٧	
Collector - Emitter Saturation Voltage	V _{CE(sat)}	$I_C = 40A$, $V_{GE} = 15V$ $T_j = 25$ °C $T_j = 175$ °C	-	1.4 1.6	1.8 -	V	

ullet IGBT Electrical Characteristics (at $T_j = 25$ °C unless otherwise specified)

Doromotor	Symbol	Conditions	Values			Unit
Parameter	1 drameter Symbol Conditions		Min.	Тур.	Max.	
Input Capacitance	C _{ies}	V _{CE} = 30V	-	2340	-	
Output Capacitance	C _{oes}	$V_{GE} = 0V$	-	55	-	pF
Reverse Transfer Capacitance	C_{res}	f = 1MHz	-	43	-	
Total Gate Charge	Q_g	V _{CE} = 300V	-	98	-	
Gate - Emitter Charge	Q_{ge}	I _C = 40A	-	20	-	nC
Gate - Collector Charge	Q_{gc}	V _{GE} = 15V	-	38	-	
Turn - on Delay Time	t _{d(on)}	$I_C = 40A, V_{CC} = 400V$	-	53	-	
Rise Time	t _r	$V_{GE} = 15V, R_{G} = 10\Omega$	-	34	-	no
Turn - off Delay Time	t _{d(off)}	T _j = 25°C	-	227	-	ns
Fall Time	t _f	Inductive Load	-	204	-	
Turn - on Switching Loss	E _{on}	*Eon includes diode	-	1.11	-	
Turn - off Switching Loss	E _{off}	reverse recovery	-	1.68	-	mJ
Turn - on Delay Time	t _{d(on)}	$I_C = 40A, V_{CC} = 400V$	-	48	-	
Rise Time	t _r	$V_{GE} = 15V, R_{G} = 10\Omega$	-	66	-	no
Turn - off Delay Time	t _{d(off)}	T _j = 175°C	-	255	-	ns
Fall Time	t _f	Inductive Load	-	310	-	l
Turn - on Switching Loss	E _{on}	*Eon includes diode	-	1.51	-	m l
Turn - off Switching Loss	E _{off}	reverse recovery	-	2.30	-	mJ
		$I_C = 160A, V_{CC} = 480V$				
Reverse Bias Safe Operating Area	RBSOA	$V_P = 600V, V_{GE} = 15V$	FU	FULL SQUARE		
		$R_G = 60\Omega, T_j = 175^{\circ}C$				

•FRD Electrical Characteristics (at $T_j = 25$ °C unless otherwise specified)

Parameter	Symbol	Conditions	Values			Unit
Parameter			Min.	Тур.	Max.	Offic
Diode Forward Voltage	V_{F}	$I_F = 20A$ $T_j = 25$ °C $T_j = 175$ °C	-	1.45 1.25	1.9 -	V
Diode Reverse Recovery Time	t _{rr}	$I_F = 20A$ $V_{CC} = 400V$ $di_F/dt = 200A/\mu s$ $T_j = 25^{\circ}C$	-	58	-	ns
Diode Peak Reverse Recovery Current	I _{rr}		-	6.3	-	A
Diode Reverse Recovery Charge	Q_{rr}		-	0.20	-	μC
Diode Reverse Recovery Energy	E _{rr}		-	7.4	-	μJ
Diode Reverse Recovery Time	t _{rr}	$I_F = 20A$ $V_{CC} = 400V$ $di_F/dt = 200A/\mu s$ $T_j = 175^{\circ}C$	-	256	-	ns
Diode Peak Reverse Recovery Current	l _{rr}		-	10.4	-	Α
Diode Reverse Recovery Charge	Q_{rr}		-	1.35	-	μC
Diode Reverse Recovery Energy	E _{rr}		-	146.5	-	μJ

Fig.1 Power Dissipation vs. Case Temperature

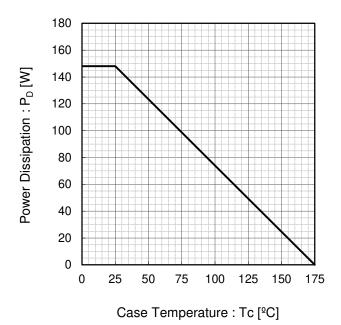


Fig.2 Collector Current vs. Case Temperature

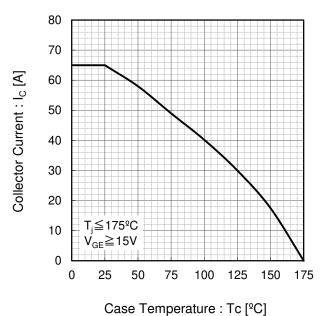


Fig.3 Forward Bias Safe Operating Area

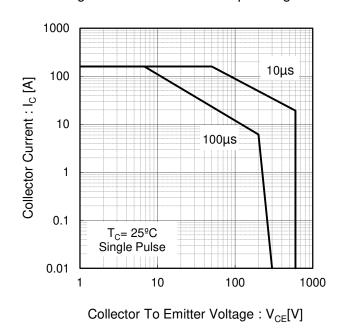
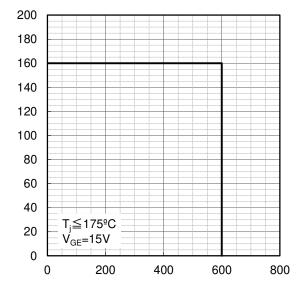


Fig.4 Reverse Bias Safe Operating Area



Collector To Emitter Voltage : $V_{CE}[V]$

Collector Current : I_C [A]

Fig.5 Typical Output Characteristics

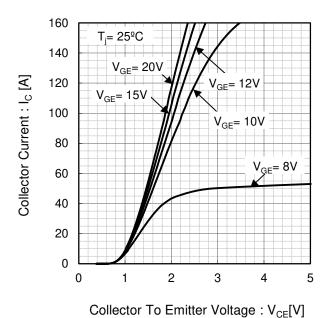
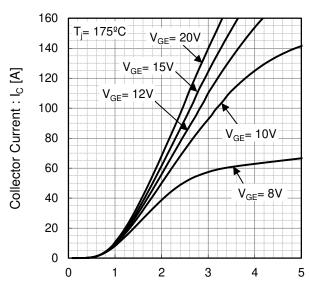


Fig.6 Typical Output Characteristics



Collector To Emitter Voltage: V_{CE}[V]

Fig.7 Typical Transfer Characteristics

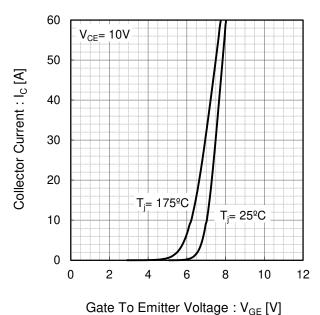
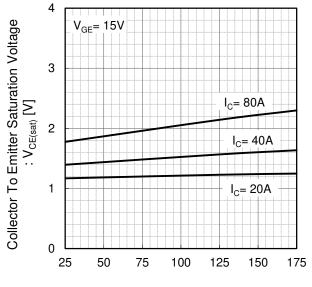


Fig.8 Typical Collector To Emitter Saturation Voltage vs. Junction Temperature



Junction Temperature : T_i [°C]

Fig.9 Typical Collector To Emitter Saturation Voltage vs. Gate To Emitter Voltage

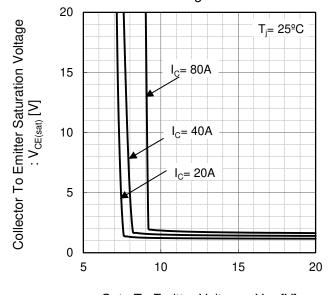
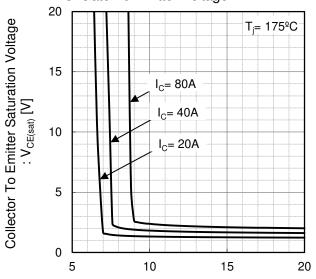


Fig.10 Typical Collector To Emitter Saturation Voltage vs. Gate To Emitter Voltage

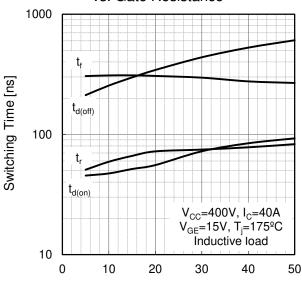


Gate To Emitter Voltage: V_{GE} [V]

Gate To Emitter Voltage : $V_{\text{GE}}\left[V\right]$

Fig.11 Typical Switching Time vs. Collector Current 1000 Switching Time [ns] $t_{d(off)}$ 100 V_{CC} =400V, V_{GE} =15V R_{G} =10 Ω , T_{j} =175 $^{\circ}$ C Inductive load 10 0 10 20 30 40 50 70 80 Collector Current : I_C [A]

Fig.12 Typical Switching Time vs. Gate Resistance



Gate Resistance : $R_G[\Omega]$

Fig.13 Typical Switching Energy Losses vs. Collector Current 10 Switching Energy Losses [mJ] $\mathsf{E}_{\mathsf{off}}$ 1 E_{on} 0.1 V_{CC} =400V, V_{GE} =15V R_{G} =10 Ω , T_{j} =175 $^{\circ}$ C Inductive load 0.01 0 10 20 30 40 50 60 70 80 Collector Current : I_C [A]

vs. Gate Resistance 10 Switching Energy Losses [mJ] 1 E_{on} 0.1 V_{CC} =400V, I_{C} =40A V_{GE} =15V, T_{j} =175 $^{\circ}$ C Inductive load 0.01 0 10 20 30 40 50 Gate Resistance : $R_G[\Omega]$

Fig.14 Typical Switching Energy Losses

Fig.15 Typical Capacitance vs. Collector To Emitter Voltage 10000 Cies 1000 Capacitance [pF] Coes 100 10 f=1MHz $V_{GE}=0V$ T_i=25°C 0.01 0.1 10 100 Collector To Emitter Voltage: V_{CE}[V]

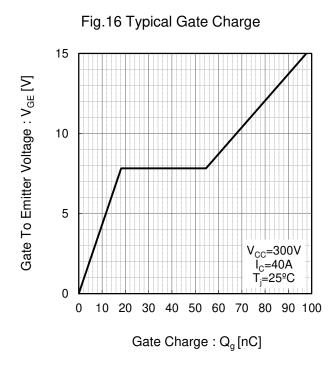


Fig.17 Typical Diode Forward Current vs. Forward Voltage

80

40

T_j 175°C

T_j 25°C

0

0

0

0

T_j 175°C

T_j 25°C

T_j 25°C

Fig.18 Typical Diode Reverse Recovery Time vs. Forward Current 400 V_{CC} =400V di_F/dt=200A/µs Reverse Recovery Time: t_{rr} [ns] Inductive load 300 T_i= 175ºC 200 100 T_i= 25ºC 0 10 20 30 50 Forward Current : I_F [A]

Fig.19 Typical Diode Reverse Recovery Current vs. Forward Current

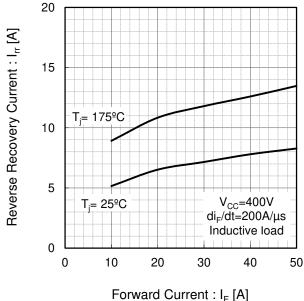
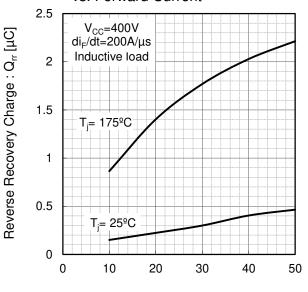


Fig.20 Typical Diode Reverse Recovery Charge vs. Forward Current



Forward Current : I_F [A]

Fig.21 IGBT Transient Thermal Impedance

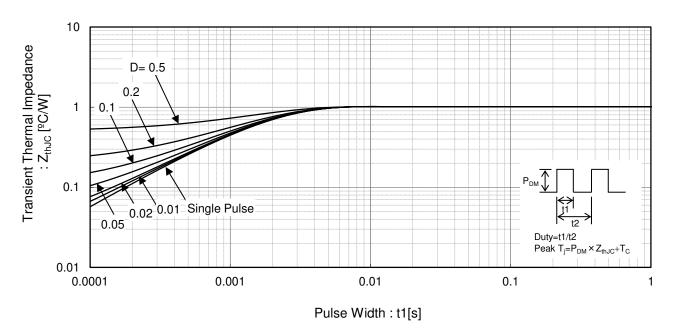
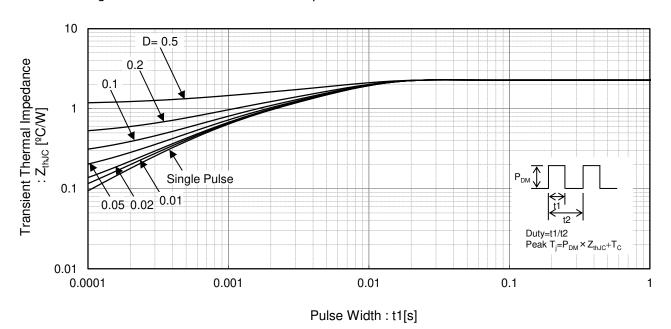


Fig.22 Diode Transient Thermal Impedance





●Inductive Load Switching Circuit and Waveform

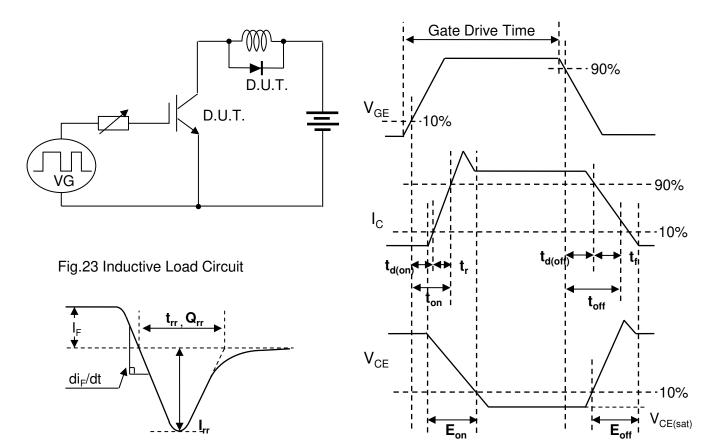


Fig.25 Diode Reverce Recovery Waveform

Fig.24 Inductive Load Waveform

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